

电流模式脉宽调制 (PWM) 控制器

查询样品: [UC1843A-DIE](#)

特性

- 抗辐射: **30kRad (Si)** 电离总剂量效应 (TID) ⁽¹⁾
 - 针对离线和直流至直流 (DC-DC) 转换器进行了优化
 - 低启动电流
 - 修整的振荡器放电电流
 - 自动前馈补偿
 - 逐脉冲电流限制
 - 增强型负载响应特性
 - 带有滞后功能的欠压闭锁
 - 双脉冲抑制
 - 高电流推挽式输出
 - 内部修整的带隙基准
 - 低 R_O 误差放大器
- (1) 抗辐射性是基于初始器件鉴定剂量率等于每秒 10mrad 时的典型值。提供辐射批次验收测试 — 详细信息请联系厂家。

说明

UC1843A-DIE 是一个用于 UC1843-DIE 的引脚兼容改进版本的引脚。提供控制电流模式开关模式电源的必要特性。

ORDERING INFORMATION⁽¹⁾

PRODUCT	PACKAGE DESIGNATOR	PACKAGE	ORDERABLE PART NUMBER	PACKAGE QUANTITY
UC1843A	TD	Bare die in waffle pack ⁽²⁾	UC1843AVTD1	100
			UC1843AVTD2	10

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Processing is per the Texas Instruments space production baseline and is in compliance with the Texas Instruments Quality Control System in effect at the time of manufacture. Electrical screening consists of DC parametric and functional testing at room temperature only. Unless otherwise specified by Texas Instruments AC performance and performance over temperature is not warranted. Visual Inspection is performed in accordance with MIL-STD-883 Test Method 2010 Condition B at 75X minimum.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

BARE DIE INFORMATION

DIE THICKNESS	BACKSIDE FINISH	BACKSIDE POTENTIAL	BOND PAD METALLIZATION COMPOSITION	BOND PAD THICKNESS
10.5 mils.	Silicon with backgrind	Floating	AlCu2%	2000 nm

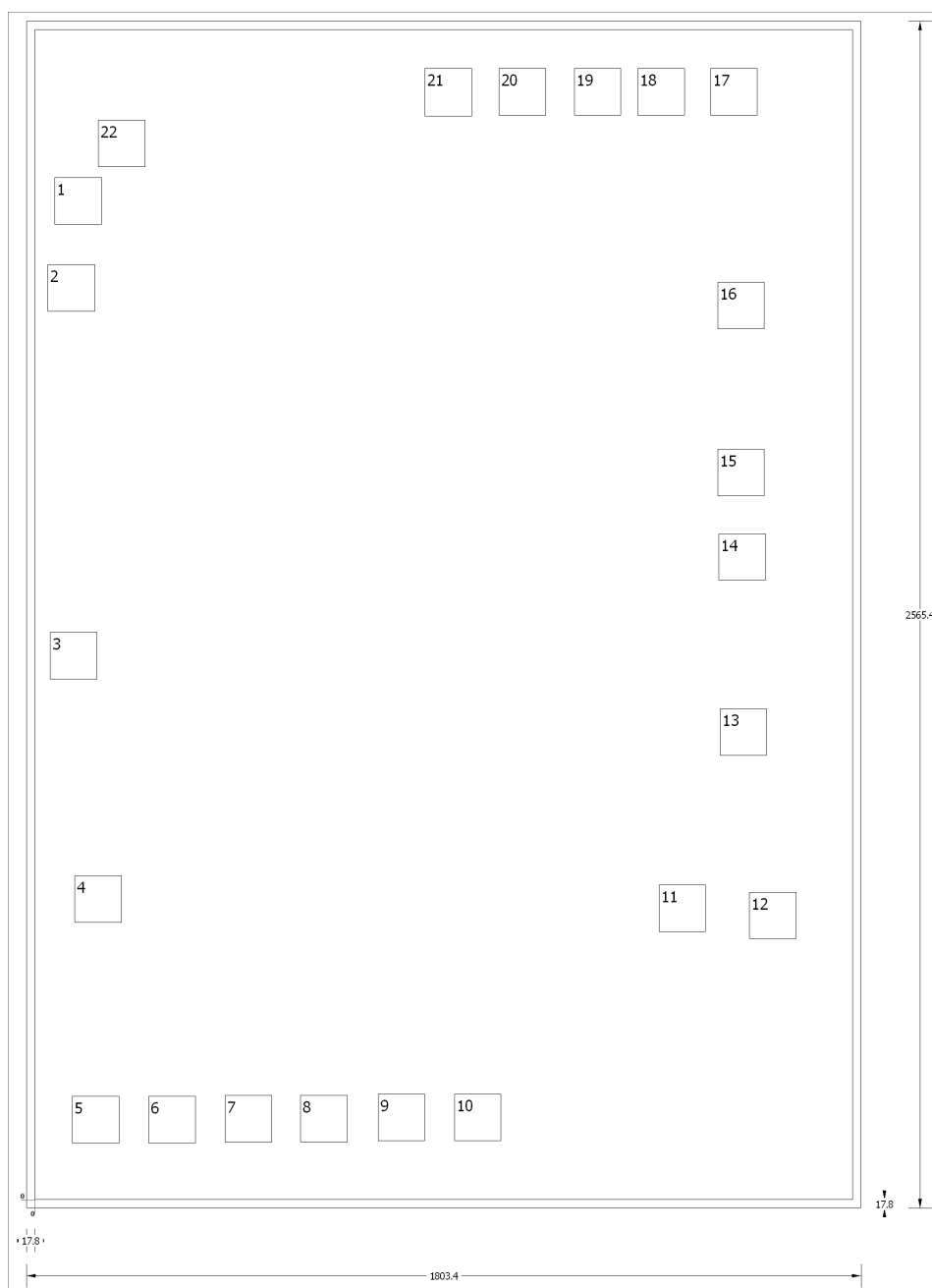


Table 1. Bond Pad Coordinates in Microns

DESCRIPTION	PAD NUMBER	X MIN	Y MIN	X MAX	Y MAX
Comp	1	43.18	2108.2	144.78	2209.8
VFB	2	27.94	1920.24	129.54	2021.84
ISENSE	3	33.02	1125.22	134.62	1226.82
RT/CT	4	86.36	599.44	187.96	701.04
N/C	5	81.28	121.92	182.88	223.52
N/C	6	246.38	121.92	347.98	223.52
N/C	7	411.48	124.46	513.08	226.06
N/C	8	574.04	124.46	675.64	226.06
N/C	9	741.68	127	843.28	228.6
N/C	10	906.78	127	1008.38	228.6
Gnd	11	1348.74	579.12	1450.34	680.72
Gnd	12	1544.32	563.88	1645.92	665.48
Output	13	1480.82	960.12	1582.42	1061.72
VCC	14	1478.28	1338.58	1579.88	1440.18
VCC	15	1475.74	1521.46	1577.34	1623.06
VREF	16	1475.74	1882.14	1577.34	1983.74
N/C	17	1460.5	2344.42	1562.1	2446.02
N/C	18	1303.02	2344.42	1404.62	2446.02
N/C	19	1165.86	2344.42	1267.46	2446.02
N/C	20	1003.3	2344.42	1104.9	2446.02
N/C	21	843.28	2341.88	944.88	2446.02
N/C	22	137.16	2232.66	238.76	2334.26

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
UC1843AVTD1	Active	Production	null (null) 0	100 NOT REQUIRED	Yes	Call TI	N/A for Pkg Type	25 to 25	
UC1843AVTD1.A	Active	Production	null (null) 0	100 NOT REQUIRED	Yes	Call TI	N/A for Pkg Type	25 to 25	
UC1843AVTD2	Active	Production	null (null) 0	10 NOT REQUIRED	Yes	Call TI	N/A for Pkg Type	25 to 25	
UC1843AVTD2.A	Active	Production	null (null) 0	10 NOT REQUIRED	Yes	Call TI	N/A for Pkg Type	25 to 25	

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF UC1843A-DIE :

- Enhanced Product : [UC1843A-EP](#)
- Space : [UC1843A-SP](#)

NOTE: Qualified Version Definitions:

- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

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